

HSEC8-149-01-L-DV-A



HSEC8-DV SERIES

(0,80 mm) .0315"

VERTICAL EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-DV

Insulator Material: Black Liquid Crystal Polymer
Contact: BeCu
Plating: Au or Sn over 50µ" (1,27 µm) Ni
Current Rating: 2.8 A per pin (2 adjacent pins powered)
Operating Temp: -55°C to +125°C
Card Insertion Depth: (3,15 mm) .125" nominal
RoHS Compliant: Yes

Processing:

Lead-Free Solderable: Yes
SMT Lead Coplanarity: (0,10 mm) .004" max (10-60)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Mates with: 1,60 mm thick cards, ECDP, HSC8



HIGH SPEED CABLE APPLICATIONS

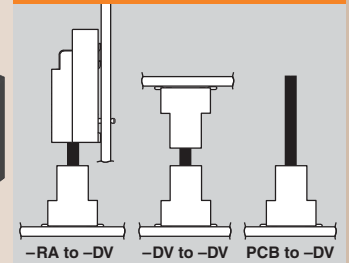


HSEC8	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
7,98 mm Stack Height		
Single-Ended Signaling	8 GHz / 16 Gbps	17 GHz / 34 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	15.5 GHz / 31 Gbps

*Performance data includes effects of a non-optimized PCB.
 **Test board losses de-embedded from performance data.
 Complete test data available at www.samtec.com?HSEC8-DV or contact sig@samtec.com

Mates with (1,60 mm) .062"

BOARD-TO-BOARD APPLICATIONS



HSEC8 - 1 POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - OTHER OPTION

09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100
 (13, 25, 49 only available with -L or -L2 option;
 09 only available with -L2 option;
 37 only available with -L option)

-01
 = (1,60 mm) .062" thick card
-03
 = (2,36 mm) .093" thick card

-L
 = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail
-S
 = 30µ" (0,76 µm) Gold on contact, Matte Tin on tail (Requires -80 & -BL)

-K
 = (7,01 mm) .276" DIA Polyimide Film Pick & Place Pad (with -01 card)
 = (6,25 mm) .246" DIA Polyimide Film Pick & Place Pad (with -03 card)

-BL
 = Board Locks (40, 50, 60, 80 only) (Other sizes available. Contact Samtec.)

-L
 = Latching Option (13, 25, 37, 49 only) (For use with EEDP)

-L2
 = ECDP Latching (09, 13, 25, 49 only) (For use with ECDP)

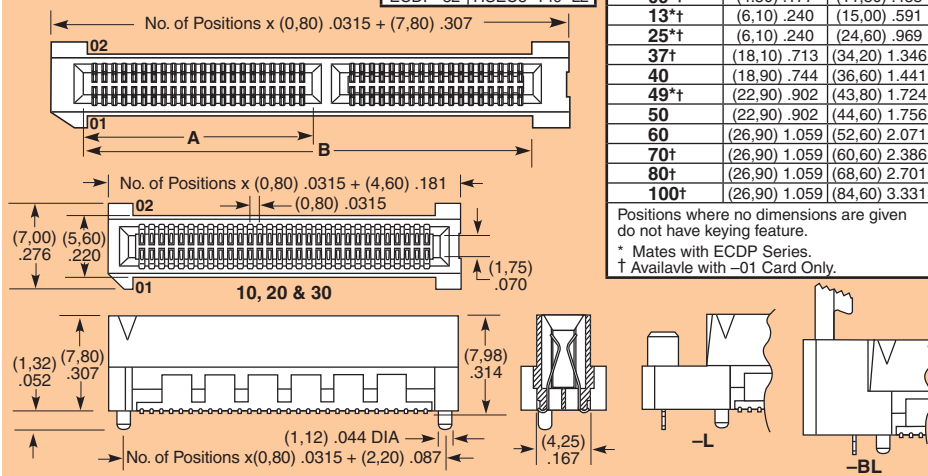
-WT
 = Weld tab

-TR
 = Tape & Reel (09 - 70 only)

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

POSITIONS PER ROW	A	B
09*†	(4,50) .177	(11,80) .458
13*†	(6,10) .240	(15,00) .591
25*†	(6,10) .240	(24,60) .969
37*†	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49*†	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70*†	(26,90) 1.059	(60,60) 2.386
80*†	(26,90) 1.059	(68,60) 2.701
100*†	(26,90) 1.059	(84,60) 3.331

Positions where no dimensions are given do not have keying feature.
 * Mates with ECDP Series.
 † Available with -01 Card Only.



OTHER SOLUTIONS

- Standard high speed interface cards for 19 mm, 25 mm & 30 mm mated heights, single-ended & differential applications. See HSC8 Series.

ALSO AVAILABLE (MOQ Required)

- Guide rails
- Pass-through options
- Other platings
- Custom cards for low-cost stack height customization
- Samtec supplied card layout/artwork to make your own cards
- Specialty card shapes

Contact Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.
Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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